

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 41 of the application as follows:

ABSTRACT OF THE DISCLOSURE

A method and apparatus for application of adhesive tape to semiconductor devices are disclosed. A first adhesively coated tape material length is supplied to a first die associated with a cutting and application mechanism. A second length of adhesively coated tape material is also provided to a second die of the cutting and application mechanism. A plurality of LOC leadframes is supplied sequentially through the application structure to apply a first decal cut from the first tape material to a first die site at a first location and to apply a second decal cut from the second tape material to a second die site at a second location.